

Temitope Theophilus Dele-Afolabi

List of Publications by Year in descending order

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26
papers

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26
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376
citing authors

#	ARTICLE	IF	CITATIONS
1	Mechanical Properties of Longitudinal Basalt/Woven-Glass-Fiber-reinforced Unsaturated Polyester-Resin Hybrid Composites. <i>Polymers</i> , 2020, 12, 2211.	2.0	87
2	Research trend in the development of macroporous ceramic components by pore forming additives from natural organic matters: A short review. <i>Ceramics International</i> , 2017, 43, 1633-1649.	2.3	58
3	Investigating the effect of isothermal aging on the morphology and shear strength of Sn-5Sb solder reinforced with carbon nanotubes. <i>Journal of Alloys and Compounds</i> , 2015, 649, 368-374.	2.8	43
4	Impact of different isothermal aging conditions on the IMC layer growth and shear strength of MWCNT-reinforced Sn-5Sb solder composites on Cu substrate. <i>Journal of Alloys and Compounds</i> , 2019, 808, 151714.	2.8	34
5	Investigating the effect of porosity level and pore former type on the mechanical and corrosion resistance properties of agro-waste shaped porous alumina ceramics. <i>Ceramics International</i> , 2017, 43, 8743-8754.	2.3	28
6	Microstructure evolution and hardness of MWCNT-reinforced Sn-5Sb/Cu composite solder joints under different thermal aging conditions. <i>Microelectronics Reliability</i> , 2020, 110, 113681.	0.9	28
7	Microstructural and shear strength properties of GNSs-reinforced Sn-1.0Ag-0.5Cu (SAC105) composite solder interconnects on plain Cu and ENIAg surface finish. <i>Journal of Materials Research and Technology</i> , 2021, 15, 2497-2506.	2.6	25
8	Growth kinetics of intermetallic layer in lead-free Sn-5Sb solder reinforced with multi-walled carbon nanotubes. <i>Journal of Materials Science: Materials in Electronics</i> , 2015, 26, 8249-8259.	1.1	23
9	Effect of agro-waste pore formers on the microstructure, hardness, and tensile properties of porous alumina ceramics. <i>International Journal of Applied Ceramic Technology</i> , 2018, 15, 1060-1071.	1.1	16
10	Significant effect of rice husk and sugarcane bagasse pore formers on the microstructure and mechanical properties of porous Al ₂ O ₃ /Ni composites. <i>Journal of Alloys and Compounds</i> , 2018, 743, 323-331.	2.8	15
11	Agro-waste shaped porous Al ₂ O ₃ /Ni composites: Corrosion resistance performance and artificial neural network modelling. <i>Materials Characterization</i> , 2018, 142, 77-85.	1.9	14
12	Tensile Strength and Moisture Absorption of Sugar Palm-Polyvinyl Butyral Laminated Composites. <i>Polymers</i> , 2020, 12, 1923.	2.0	14
13	Influence of porous Cu interlayer on the intermetallic compound layer and shear strength of MWCNT-reinforced SAC 305 composite solder joints. <i>Journal of Materials Science: Materials in Electronics</i> , 2021, 32, 4515-4528.	1.1	11
14	Tailored pore structures and mechanical properties of porous alumina ceramics prepared with corn cob pore-forming agent. <i>International Journal of Applied Ceramic Technology</i> , 2021, 18, 244-252.	1.1	10
15	Tensile strength and corrosion resistance properties of porous Al ₂ O ₃ /Ni composites prepared with rice husk pore-forming agent. <i>Ceramics International</i> , 2018, 44, 11127-11135.	2.3	9
16	Interfacial IMC evolution and shear strength of MWCNTs-reinforced Sn-5Sb composite solder joints: Experimental characterization and artificial neural network modelling. <i>Journal of Materials Research and Technology</i> , 2021, 13, 1020-1031.	2.6	9
17	Influence of multi-walled carbon nanotubes on melting temperature and microstructural evolution of Pb-free Sn-5Sb/Cu solder joint. <i>IOP Conference Series: Materials Science and Engineering</i> , 2017, 238, 012010.	0.3	7
18	Microstructural and shear strength properties of RHA-reinforced Sn-0.7Cu composite solder joints on bare Cu and ENIAg surface finish. <i>Journal of Materials Science: Materials in Electronics</i> , 2020, 31, 8316-8328.	1.1	7

#	ARTICLE	IF	CITATIONS
19	Physical and Mechanical Properties of Tilapia Scale Hydroxyapatite-Filled High-Density Polyethylene Composites. <i>Polymers</i> , 2022, 14, 251.	2.0	6
20	Interfacial microstructure evolution and shear strength of MWCNTs-reinforced Sn-1.0Ag-0.5Cu (SAC105) composite solder interconnects on plain Cu and ENIAG surface finish. <i>Journal of Materials Science: Materials in Electronics</i> , 2022, 33, 8233-8246.	1.1	6
21	Controlling the sintering response in the development of multilayered components produced via powder injection molding route—a review. <i>International Journal of Advanced Manufacturing Technology</i> , 2020, 107, 3755-3777.	1.5	2
22	Shear analysis of rice husk ash (RHA) reinforced tin–copper composite solders on electroless nickel/immersion silver (ENIAG) surfaces. <i>Materialwissenschaft Und Werkstofftechnik</i> , 2021, 52, 943-951.	0.5	2
23	Investigating the effect of sintering temperature on the microstructure and hardness of cemented tungsten carbide/steel bilayer. <i>IOP Conference Series: Materials Science and Engineering</i> , 2019, 469, 012020.	0.3	1
24	Effect of nickel addition on the microstructure and corrosion resistance properties of porous alumina composites shaped with sugarcane bagasse pore-forming agent. <i>IOP Conference Series: Materials Science and Engineering</i> , 2019, 469, 012019.	0.3	1
25	Characterization Techniques in Nanotechnology: The State of the Art. <i>Materials Horizons</i> , 2021, , 21-73.	0.3	1
26	Fabrication Methods and Characterization Techniques for Porous Ceramic Materials. , 2019, , 55-65.		0